

ELCOSINT

The future of High Temperature Interconnect

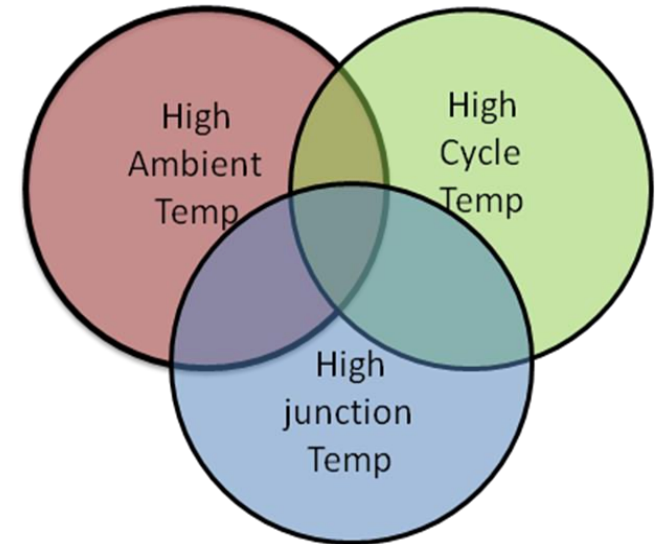
InnovateUK

- UK Government organisation
- Funding scheme for Industry
- Collaborative R&D medium to high risk
- Typically 6 to 36mths duration
- Project costs range £75k to £1.5M
- <https://www.gov.uk/government/organisations/innovate-uk>



Project Drivers

- Holistic overview of high temp assembly applications:
 - High temp components – available
 - High temp substrates – room for development
 - High temp interconnects – room for development develop



Application Breakdown for HT electronics

Project Objectives

- To develop novel printable “solder paste like” material
- High operating temperature > 225 C
- Low temperature processing
- Lead free

Facts & Figures

- 3 UK Industrial Partners
- 3 Year time frame
- £1M total project cost
- £26M expected economic benefit after 7 years
- 6 Work Packages
- 16 Deliverables
- 6 Milestones

Top Level Partner Profiles

- **National Physics Laboratory**
 - 600+ specialists in Measurement Science
 - World leading National Measurement Institute
- **Gwent Electronic Materials**
 - Long standing UK SME
 - Specialist developer of novel inks and materials for the electronics and medical diagnostic industries
- **Microsemi Semiconductor Ltd**
 - UK subsidiary of multinational company
 - Electronics packaging and system integration for high value high reliability applications such as medical and harsh environment

Target Markets

Supporting the UK initiative and focus on high value manufacturing



Automotive



Aerospace



Oil & Gas
Exploration



Power



Renewables

Points of Contact

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